

November 2014

ISL9R860PF2 8 A, 600 V, STEALTH™ Diode

Features

- Stealth Recovery t_{rr} = 28 ns (@I_F = 8 A)
- Max Forward Voltage, V_F = 2.4 V (@ T_C = 25°C)
- 600 V Reverse Voltage and High Reliability
- Avalanche Energy Rated
- RoHS Compliant

Applications

- Switch Mode Power Supplies
- · Hard Switched PFC Boost Diode
- · UPS Free Wheeling Diode
- · Motor Drive FWD
- SMPS FWD
- Snubber Diode

Description

The ISL9R860PF2 is a STEALTH $^{\text{TM}}$ diode optimized for low loss performance in high frequency hard switched applications. The STEALTH $^{\text{TM}}$ family exhibits low reverse recovery current (I $_{\text{rr}}$) and exceptionally soft recovery under typical operating conditions. This device is intended for use as a free wheeling or boost diode in power supplies and other power switching applications. The low I $_{\text{rr}}$ and short ta phase reduce loss in switching transistors. The soft recovery minimizes ringing, expanding the range of conditions under which the diode may be operated without the use of additional snubber circuitry. Consider using the STEALTH $^{\text{TM}}$ diode with an SMPS IGBT to provide the most efficient and highest power density design at lower cost.

Package Symbol







CATHODE ANODE

Device Maximum Ratings T_C= 25°C unless otherwise noted

Symbol	Parameter	Ratings	Unit
V_{RRM}	Peak Repetitive Reverse Voltage	600	V
V_{RWM}	Working Peak Reverse Voltage	600	V
V _R	DC Blocking Voltage	600	V
I _{F(AV)}	Average Rectified Forward Current (T _C = 75°C)	8	Α
I _{FRM}	Repetitive Peak Surge Current (20 kHz Square Wave)	16	Α
I _{FSM}	Nonrepetitive Peak Surge Current (Halfwave 1 Phase 60 Hz)	100	Α
P _D	Power Dissipation	26	W
E _{AVL}	Avalanche Energy (1 A, 40 mH)	20	mJ
T _J , T _{STG}	Operating and Storage Temperature Range	-55 to 175	°C
T _L	Maximum Temperature for Soldering Leads at 0.063in (1.6mm) from Case for 10s	300	°C
	Leads at 0.000iii (1.0iiiii) iioiii Case ioi 103	300	

CAUTION: Stresses above those listed in "Device Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

Part Num	ber	Top Mark	Package	Packing Method	Reel Size	Tape Width		Qι	Quantity	
ISL9R860PF2 ISL9I		ISL9R860PF2	TO-220F-2L	Tube N/A		N/A			50	
Electric	cal C	Characteris	Stics T _C = 25°C	unless otherwise no	oted					
Symbol	Parameter		Test Conditions		Min	Тур	Max	Unit		
•	Cha	racteristics					, ,,			
I _R Instantaneous Reverse Current		V _R = 600 V	T _C = 25°C	_	_	100	μА			
		VR = 000 V	$T_{\rm C} = 125^{\circ}{\rm C}$	-	-	1.0	mA			
					1 0	<u>I</u>	l			
		racteristics			T					
V_{F}	Insta	Instantaneous Forward Voltage		I _F = 8 A	$T_C = 25^{\circ}C$	-	2.0	2.4	V	
					T _C = 125°C	-	1.6	2.0	V	
Dynamic	: Cha	racteristics								
CJ	Junction Capacitance $V_R = 10 \text{ V}$					-	30		pF	
Switchin	na Ch	aracteristics				•			_	
	t _{rr} Reverse Recovery Time		$I_F = 1 \text{ A, di}_F/\text{dt} = 10$	00 A/us. V _P = 30 V	' -	18	25	ns		
"			$I_F = 8 \text{ A}, \text{ di}_F/\text{dt} = 100 \text{ A/}\mu\text{s}, \text{ V}_R = 30 \text{ V}$		-	21	30	ns		
t _{rr}	Reverse Recovery Time			$I_F = 8 \text{ A},$ $di_F/dt = 200 \text{ A/}\mu\text{s},$ $V_R = 390 \text{ V}, T_C = 25^{\circ}\text{C}$		-	28	-	ns	
I _{rr}	Maximum Reverse Recovery Current		-			3.2	-	Α		
Q _{rr}	Reverse Recovery Charge		-			50	-	nC		
t _{rr}	Reve	erse Recovery Ti	me	I _F = 8 A,		-	77	-	ns	
S	Softr	Softness Factor (t _b /t _a)		$di_F/dt = 200 A/\mu s,$		-	3.7	-		
I _{rr}	Maximum Reverse Recovery Current Reverse Recovery Charge		$V_R = 390 \text{ V},$		-	3.4	-	Α		
Q _{rr}			$T_{\rm C} = 125^{\circ}{\rm C}$		-	150	-	nC		
t _{rr}		erse Recovery Ti		I _F = 8 A,		-	53	-	ns	
S	Softr	Softness Factor (t _b /t _a)		$di_F/dt = 600 A/\mu s$,		-	2.5	-		
I _{rr}	Maximum Reverse Recovery Current Reverse Recovery Charge		$V_{R} = 390 \text{ V},$ $T_{C} = 125^{\circ}\text{C}$		-	6.5	-	Α		
Q _{rr}						195	-	nC		
dl _M /dt	Maximum di/dt during t _b						500	-	A/µs	
Thermal	Cha	racteristics								
· · · · · · · · · · · · · · · ·	Thermal Resistance Junction to Case									
$R_{\theta JC}$	Ther	mal Resistance	Junction to Case			/ -	-	4.8	°C/W	

Typical Performance Curves 16 100 175°C 14 150°C REVERSE CURRENT (µA) 12 FORWARD CURRENT (A) 10 8 100°C 6 25°C 2 0.1 1.25 1.5 1.75 0.25 0.5 0.75 200 V_F, FORWARD VOLTAGE (V) V_R, REVERSE VOLTAGE (V) Figure 1. Forward Current vs Forward Voltage Figure 2. Reverse Current vs Reverse Voltage V_R = 390V, T_J = 125°C $V_R = 390V, T_J = 125$ °C 70 $t_b AT d_F/dt = 200A/\mu s, 500A/\mu s, 800A/\mu s$ 60 RECOVERY TIMES (ns) 60 RECOVERY TIMES 50 50 40 40 30 30 20 20 10 10 8 10 300 400 500 600 700 800 di_F/dt, CURRENT RATE OF CHANGE (A/ μ s) 100 I_F, FORWARD CURRENT (A) Figure 3. t_a and t_b Curves vs Forward Current Figure 4. t_a and t_b Curves vs di_F/dt $V_R = 390V, T_J = 125$ °C $di_F/dt = 800A/\mu s$ $V_R = 390V, T_J = 125$ °C MAX REVERSE RECOVERY CURRENT (A) 10 12 In, MAX REVERSE RECOVERY CURRENT 9 10 8 $di_F/dt = 500A/\mu s$ 7 6 6 5 $di_F/dt = 200A/\mu s$ 4 3 10 12

Figure 5. Maximum Reverse Recovery Current vs **Forward Current**

I_F, FORWARD CURRENT (A)

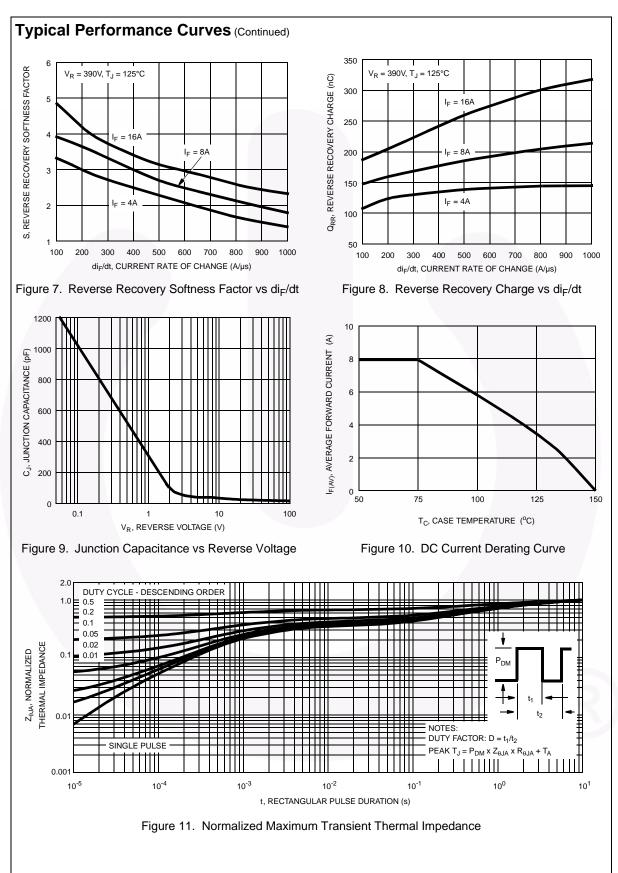
Figure 6. Maximum Reverse Recovery Current vs di_F/dt

di_E/dt, CURRENT RATE OF CHANGE (A/µs)

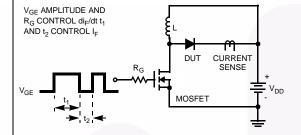
400 500 600 700

100 200 800

900 1000



Test Circuits and Waveforms



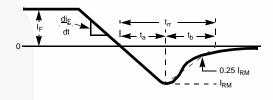
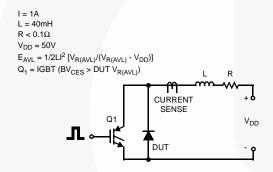


Figure 12. t_{rr} Test Circuit

Figure 13. t_{rr} Waveforms and Definitions



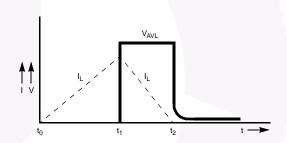


Figure 14. Avalanche Energy Test Circuit

Figure 15. Avalanche Current and Voltage Waveforms

Mechanical Dimensions

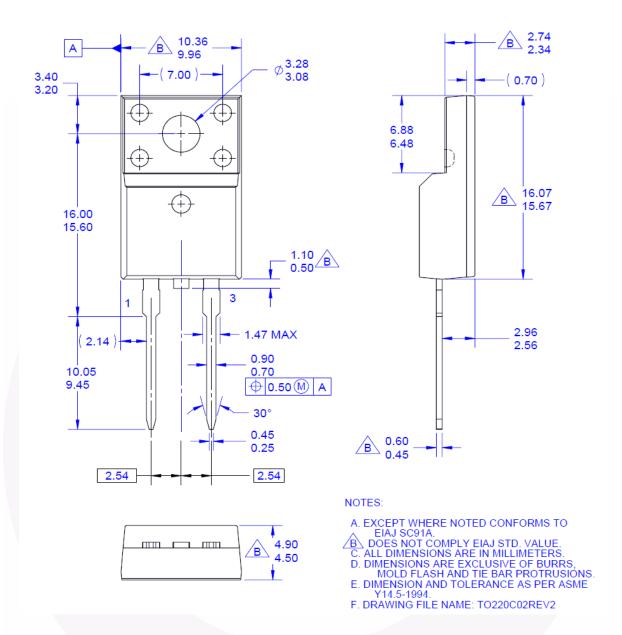


Figure 16. TO-220F 2L - 2LD; TO220; MOLDED; FULL PACK

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Rev. 171